### Table

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<tr>
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<td>×</td>
<td>NO</td>
<td>+/-0.0</td>
</tr>
</tbody>
</table>

### Dimensions
- **1910 mil**
- **2400 mil**

### Notes
- **Layer Name**: 6 ASSEMBLY HOM
- **Overall Board Thickness**: 62 Mil
- **Soldermask Color**: Red
- **SILscreen Color**: White
- **Drill hole tolerance**: +/- 3 Mil
- **Copper/Spacing Clearances**: 5/5 Mil

### PCB Information
- **Company**: T3-SVA
- **PCB Part Number**: DK16
- **Rev**: 2
- **Date**: 12/10/14

### PCB Edges
- **62 Mil**
- **TOP: 1 OZ PREPREG**
- **INTERNAL: 1 OZ 37-40 Mil FR4**
- **BOTTOM: 1 OZ PREPREG**
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